

Docket No.: 1999P2628

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : LOTHAR BAUCH ET AL.

Filed : CONCURRENTLY HEREWITH

Title : STACKED VIA WITH SPECIALLY DESIGNED LANDING PAD FOR  
INTEGRATED SEMICONDUCTOR STRUCTURES

#41BDS  
Anoum  
8/29/02

10/082554  
JC986 U.S. PTO  
02/25/02

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent 5,591,673 (Chao et al.), dated January 7, 1997;

U.S. Patent 5,894,170 (Ikshikawa), dated April 13, 1999;

German Published Non-Prosecuted Patent Application DE 198 02 161 A1 (inventor will be mentioned later), dated July 22, 1999, method for producing stacked vias;

International Search Report, dated January 22, 2001.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,

For Applicants

LAURENCE A. GREENBERG  
REG. NO. 29,308

Date: February 25, 2002

Lerner and Greenberg, P.A.  
Post Office Box 2480  
Hollywood, FL 33022-2480  
Tel: (954) 925-1100  
Fax: (954) 925-1101

/kf